Lenovo Product End-of-Life Processing Information

Product Category and Marketing Name:

PURPOSE:

Lenovo supports the recycling of Waste Electrical and Electronic Equipment (WEEE) for all the worldwide countries and regions Lenovo ships to. The purpose of creating this document is to provide proper methods for removing parts and general product disassembly instructions, as required by the EU WEEE Directive 2012/19/EU.

GENERAL DESCRIPTION DISASSEMBLY:

Most components can be removed easily by hand. In some cases, common household tools such as flat-head screwdrivers may be necessary. Instructions for removing parts in each product can be found in the Maintenance Manual originally provided with the product as below.

https://thinksystem.lenovofiles.com/help/topic/7D2X/sr645 maintenance_manual.pdf

MATERIALS REQUIRING SELECTIVE TREATMENT

The following table provides information on the presence of materials and components that require selective treatment as defined by the European Union WEEE Directive, 2012/19/EU Annex VII.

Substance, preparation or component	Notes
Capacitors containing polychlorinated biphenyls (PCBs) or polychlorinated terphenyls (PCT)	No capacitors contain polychlorinated biphenyls (PCBs) or polychlorinated terphenyls (PCT).
Components containing mercury	No components contain mercury.
Batteries	The server supports a Lithium battery as the CMOS battery refer to "Hardware replacement procedure" section in <i>Maintenance Manual</i> to remove the battery from the system board.
Printed circuit boards	Present in the system board, memory modules, Riser card, M.2 adapter,7mm adapters, hard disk drive backplane, power supplies, and diagnostics panel. Present also in expanded PCIe adapters (e.g. Network adapters, Storage controllers, GPU adapters) and an optional security module TPM (for geographic unique security requirements).
Toner cartridges	No components contain toner cartridges.

Plastic containing brominated flame retardants	No components contain brominated flame retardants in plastic.
Asbestos	No components contain asbestos.
Cathode ray tube (CRT)	No components contain CRT.
Chlorofluorocarbons (CFC); hydrochlorofluorocarbons (HCFC); or hydrocarbons (HC)	No components contain Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC), or hydrocarbons (HC).
Gas discharge lamps	No components contain gas discharge lamps.
Liquid crystal displays (together with their casing where appropriate) of a surface area greater than 100 square centimeters	No components contain liquid crystal displays.
External electric cables	External cables like USB, VGA, InfiniBand, SAS, and Ethernet may be present. Power line cords are required for operation.
Components containing refractory ceramic fibers	No components contain refractory ceramic fibers.
Components containing radioactive substances	No components contain radioactive substances.
Electrolyte capacitors containing substances of concern – greater than 25 mm in height or diameter or similar volume	These capacitors are present in power supply units. Electrolytic capacitors (height and/or diameter greater than 25mm) are not used on the system board.
Equipment containing gasses that are ozone depleting or have a global warming potential (GWP) above 15	No components contain gasses that are ozone depleting or have a global warming potential above 15